

SECRET

3. A photo- or heat-curable resin composition as described in claim 1 wherein at least one kind of other unsaturated compound (E) selected from other monomers and oligomers is incorporated at a rate of 100 parts or less per 100 parts by weight of the component A in addition to the components A, B, C and D.

5. A cured resin formed by curing a photo- or heat-curable resin composition as described in claim 1.

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